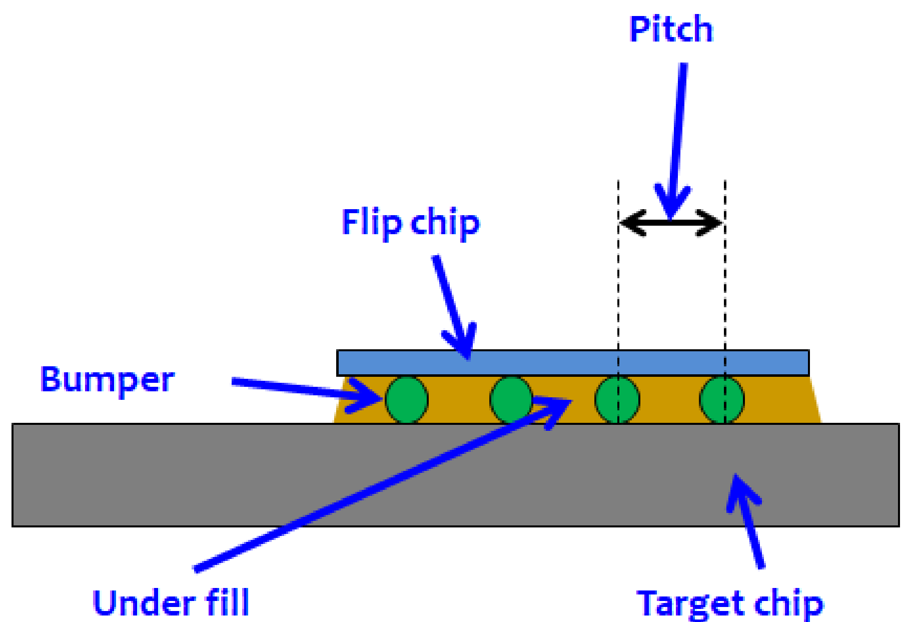
ANDANTA

Flip-Chip Bonding Service

State-of-the-art Flip-Chip Bonding Equipment in 1000 m^2 (class 1000) clean room

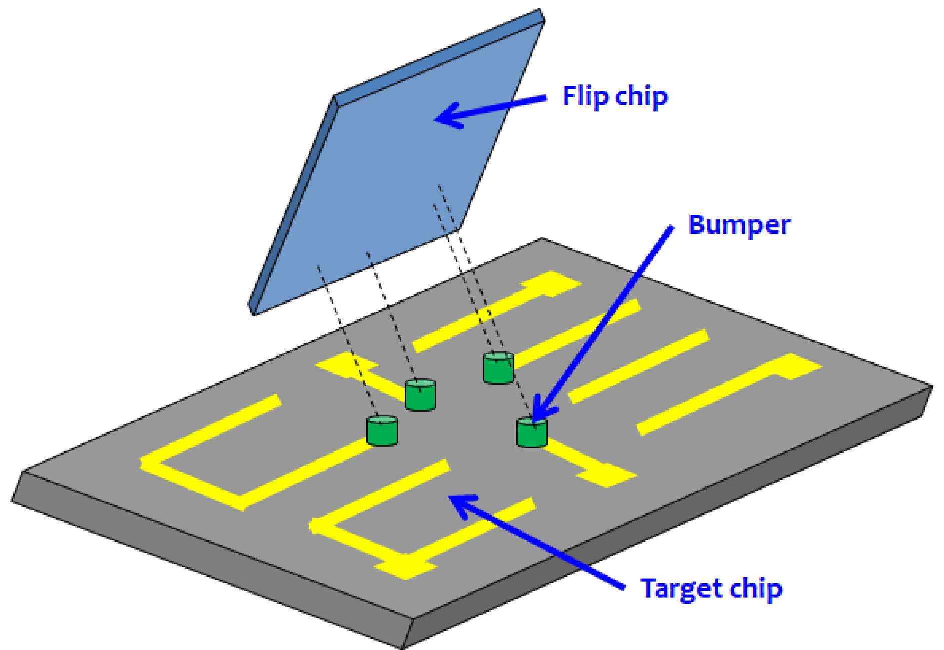
Capability

- Minimum pitch: 10µm
- Component size:
  Flip chip: 200µm ~ 60mm
  Target chip: 500µm ~ 150mm
- Gold, Gold/Tin, Indium, Polymers and adhesive
- Compound semiconductors
  Si-based device or substrate

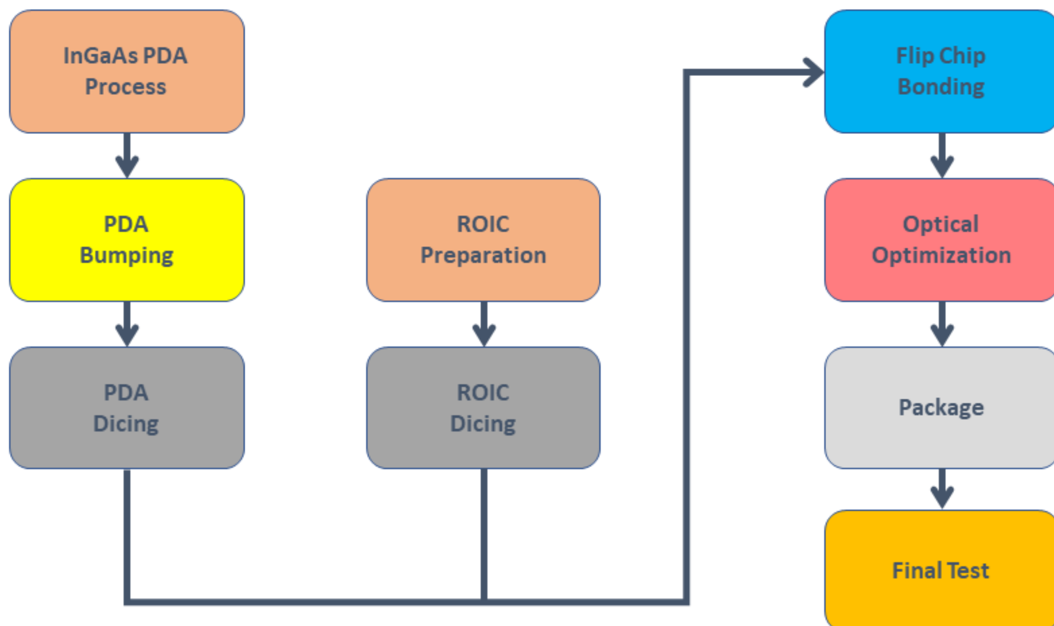


Applications

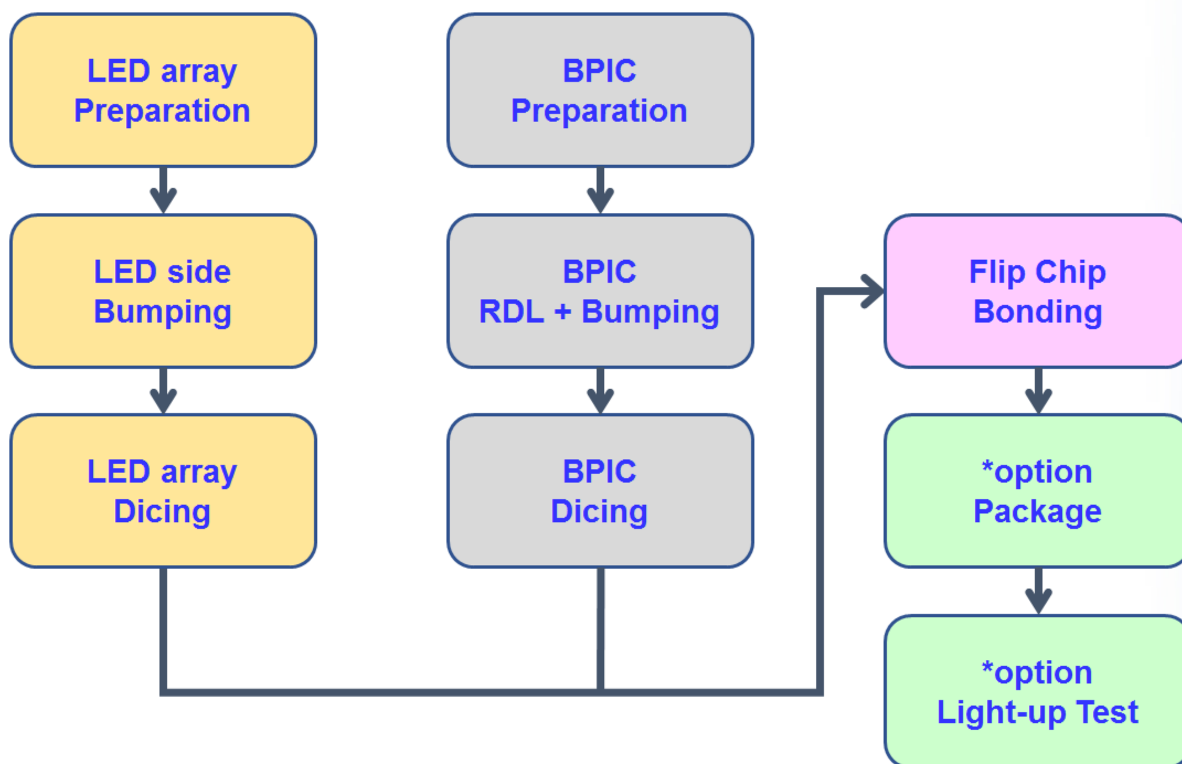
- MEMS
- Focal Plane Array
- Chip to substrate
- 3D IC
- BGA
- µLED
- Chip Stacking



Process Steps of FPA



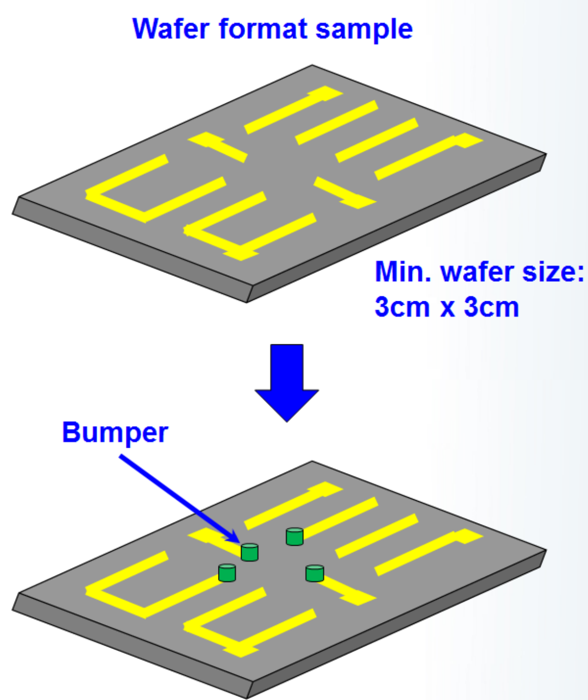
Process Steps of µLED Panel



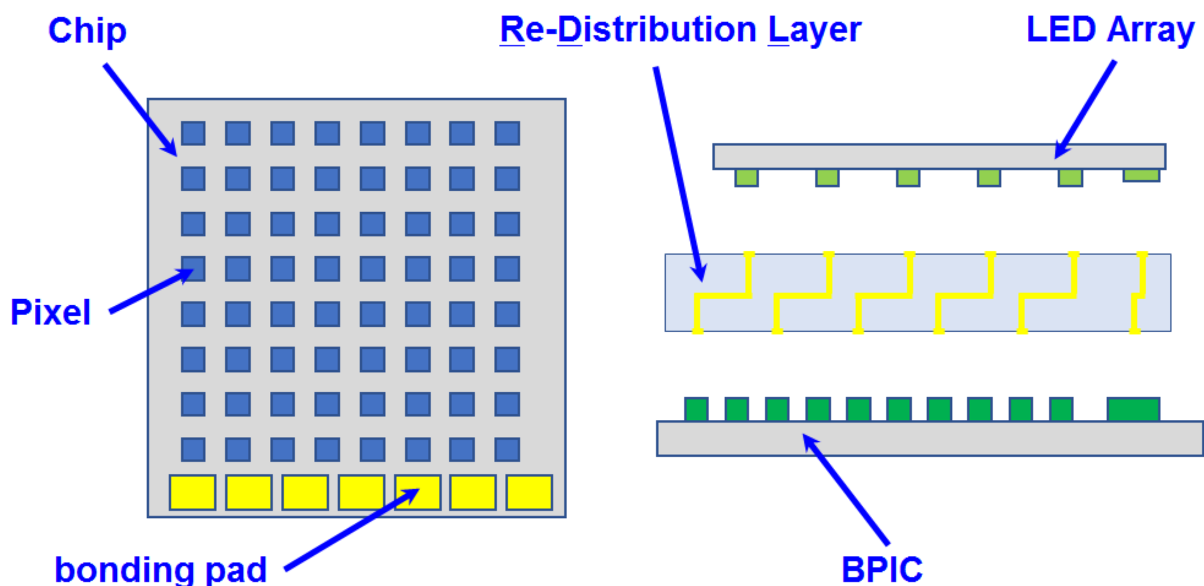
Bumping Process

Bumping process is essential to Flip-Chip Bonding.

Bumping is an advanced wafer level process technology where "bumpers" made of solder are formed on the wafers in a wafer form before the wafer is being diced into individual chips



Re-Distribution Layer



RDL is an interface to connect 2 arrays with different pixel pitch.

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